

What Is Claimed Is:

1 1. A wafer storage method for preventing bonding pad fluoridation,
2 comprising:
3 providing a shipping box for a wafer, the shipping box having at
4 least one through hole;
5 providing a packaging bag to contain the shipping box;
6 pumping air from the packaging bag and the shipping box;
7 introducing a dry inert gas into the packaging bag and the shipping
8 box until approaching atmospheric pressure; and
9 sealing the packaging bag.

1 2. The wafer storage method as claimed in claim 1, wherein air
2 inside the packaging bag and the shipping box is pumped out by a vacuum
3 packaging machine until pressure is dropped to 350-400 mmHg.

1 3. The wafer storage method as claimed in claim 1, wherein the
2 dry inert gas is nitrogen.

1 4. A wafer-shipping device, comprising:
2 a shipping box for a wafer, the shipping box having at least one
3 through hole;
4 a packaging bag to contain the shipping box; and
5 a dry inert gas filling the packaging bag and the shipping box,
6 surrounding the wafer.

1 5. The wafer-shipping device as claimed in claim 4, wherein the
2 pressure inside the shipping box is approaching atmospheric pressure.

1 6. The wafer-shipping device as claimed in claim 4, wherein the
2 dry inert gas is nitrogen.